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SHEET 1 OF 1

Form PTO 1449 U.S. DEPARTMENT OF COMMERCE (Modified) PATENT AND TRADEMARK OFFICE			ATTY DOCKET NO. 251148US0 SERIAL NO. 10/809,704				
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LISTOF	VELEK	RENCES CITED BY APP	LICANI	Yuko UCHIMARU, et al.			
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U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
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73.5	AO	2002-317049	10/31/2002	JAPAN (with English Abstract)			X
0	AP	2968244	08/20/1999	JAPAN (with English Abstract)			X
	AQ	3041424	03/10/2000	JAPAN (with translation of claim 1)			X
	AR	2002-359240	12/13/2002	JAPAN (with English Abstract)		<u> </u>	X
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U.	AT		·			<u> </u>	
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		OTHER RE	FERENCES	(Including Author, Title, Date, Pertinen	t Pages,	etc.)	•
my	AW	International Technology Roadmap for Semiconductors 2002 Update, 2002 Update Tables, page 75, "TABLE 62A MPU INTERCONNECT TECHNOLOGY REQUIREMENTS—NEAR-TERM", 2002					
m	AX	S. SHINMIYAHARA, et al., Cu-Interconnect Technology, page 227, "LATEST DEVELOPMENT OF CU WIRING TECHNIQUES", (with partial English translation)					
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	AZ				Ade	ditional Re	ferences sheet(s) attached
Examiner	<u> </u>	May 1	Male Considered 5/5/08				
*Examiner: I	nitial if	reference is considered	whether or no	ot citation is in conformance with MPEP 6 m with next communication to applicant.	09; Draw	line throug	h citation if not in